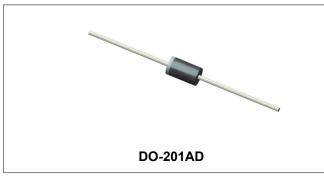






SB3100 SCHOTTKY RECTIFIER



Features

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters,
 Free Wheeling, and Polarity Protection Applications
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection
- Disk drives
- Battery charging

Maximum Ratings:

| Characteristics | Symbol | Condition | Max. | Units |
|--|--|--|------|-------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | - | 100 | V |
| Average Rectified Forward Current | I _{F (AV)} | 50% duty cycle @T _C =105°C, rectangular wave form | 3 | А |
| Peak One Cycle Non-Repetitive Surge Current | I _{FSM} | 8.3 ms, half Sine pulse, T _C =25°C | 110 | Α |

Electrical Characteristics:

| Characteristics | Symbol | Condition | Тур. | Max. | Units |
|-----------------------|-----------------|---|------|------|-------|
| Forward Voltage Drop* | V _{F1} | @ 3A, Pulse, T _J = 25 °C | 0.76 | 0.79 | V |
| | V _{F2} | @ 3A, Pulse, T _J = 125 °C | 0.65 | 0.70 | V |
| Reverse Current* | I _{R1} | @V _R = Rated V _R , Pulse, T _J = 25 °C | 0.01 | 1.0 | mA |
| | I _{R2} | @V _R = Rated V _R , Pulse, T _J = 125 °C | 0.1 | 10 | mA |
| Junction Capacitance | Ст | $@V_R = 5V, T_C = 25 °C$ $f_{SIG} = 1MHz$ | 90 | 250 | pF |

^{*} Pulse width < 300 μs, duty cycle < 2%



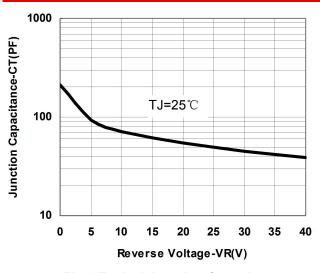




Thermal-Mechanical Specifications:

| Characteristics | Symbol | Condition | Specification | Units |
|---|-------------------|--------------|---------------|-------|
| Junction Temperature | TJ | - | -55 to +150 | °C |
| Storage Temperature | T _{stg} | - | -55 to +150 | °C |
| Typical Thermal Resistance Junction to Case | R ₀ JC | DC operation | 8 | °C/W |
| Approximate Weight | wt | - | 1.02 | g |

Ratings and Characteristics Curves



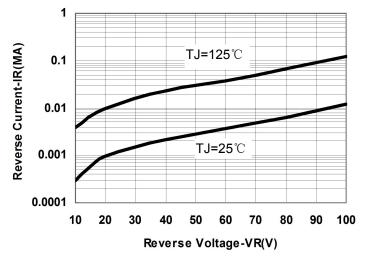


Fig.1-Typical Junction Capacitance

Fig.2-Typical Reverse Current

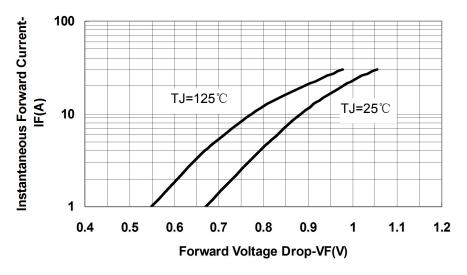


Fig.3-Typical Forward Voltage Drop Characteristics

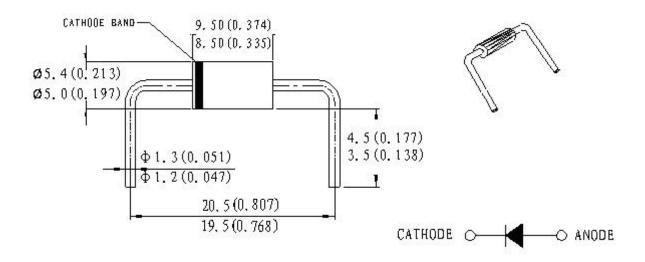
- China Germany Korea Singapore United States
 - http://www.smc-diodes.com sales@ smc-diodes.com •







Mechanical Dimensions DO-201AD(C-02)(Millimeters/Inches)



Ordering Information

| Device | Package | Shipping | |
|--------------|-----------------------------|--------------|--|
| SB3100(C-02) | DO-201AD(C-02) (Pb-Free) | 200pcs / bag | |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

 SB3100
 = Part Name

 SSG
 = SSG

 YY
 = Year

 WW
 = Week

 L
 = Lot Number

Cautions: Molding resin Epoxy resin UL:94V-0

- China Germany Korea Singapore United States
 - http://www.smc-diodes.com sales@ smc-diodes.com •







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